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Electronic Components Sourcing Information

Product Reference Information

Part Number: RB521S30-QX
Manufacturer: Nexperia USA Inc.
Package: SC-79, SOD-523
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nexperia-usa-inc/rb521s30-qx.html>

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



RB521S30-Q

200 mA low VF Schottky barrier rectifier

6 August 2026

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.2$ A
- Reverse voltage: $V_R \leq 30$ V
- Low reverse current: $I_R \leq 30$ μ A
- Ultra small and flat lead SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low current rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; $T_{sp} \leq 140$ °C; square wave	-	-	0.2	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	30	V
V_F	forward voltage	$I_F = 100$ mA	[1]	355	410	mV

[1] Pulsed test: $t_p \leq 300$ μ s; $\delta \leq 0.02$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SC-79 (SOD523)	 K $\rightarrow$ A sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
RB521S30-Q	SC-79	plastic, surface-mounted package; 2 leads; 1.2 mm x 0.8 mm x 0.6 mm body	SOD523

7. Marking

Table 4. Marking codes

Type number	Marking code
RB521S30-Q	ZB

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	30	V
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; T _{amb} ≤ 120 °C; square wave	[1]	-	0.2	A
		δ = 0.5; f = 20 kHz; T _{sp} ≤ 140 °C; square wave		-	0.2	A
I _{FSM}	non-repetitive peak forward current	t _p = 8.3 ms; half sine wave; JEDEC method; T _{j(init)} = 25 °C	[2]	-	1	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[3] [4]	-	275	mW
			[1] [4]	-	420	mW
			[5] [4]	-	500	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [2] T_j = 25 °C Prior to surge
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Reflow soldering is the only recommended soldering method.
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	455	K/W
			[1] [4] [3]	-	-	300	K/W
			[1] [5] [3]	-	-	250	K/W

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	90	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Reflow soldering is the only recommended soldering method.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [6] Soldering point of cathode tab.

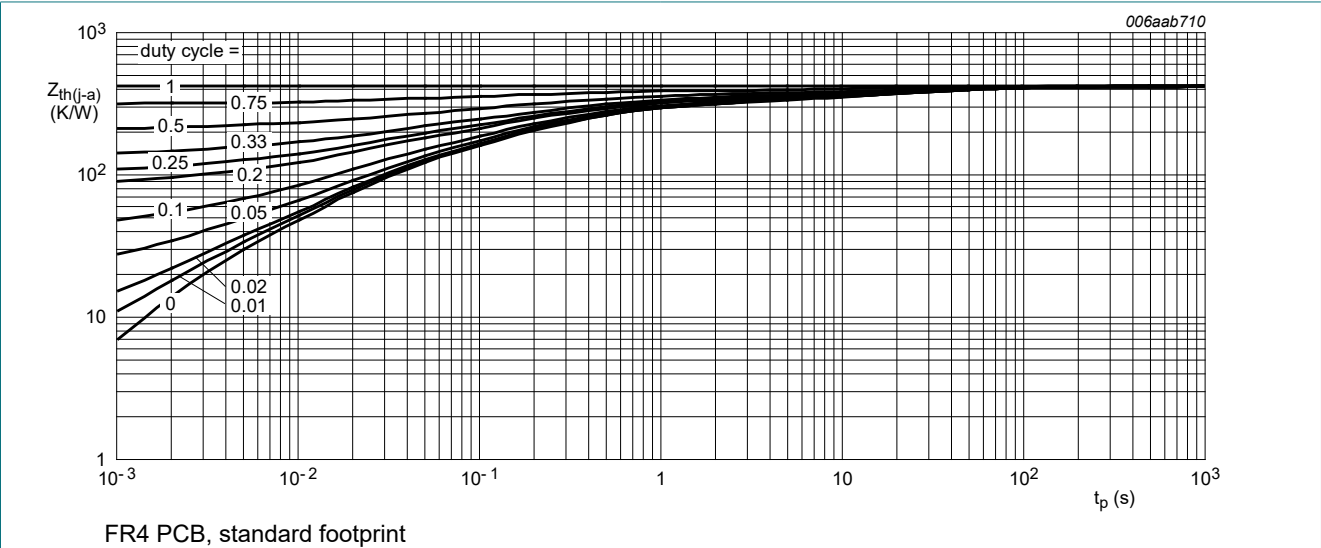


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

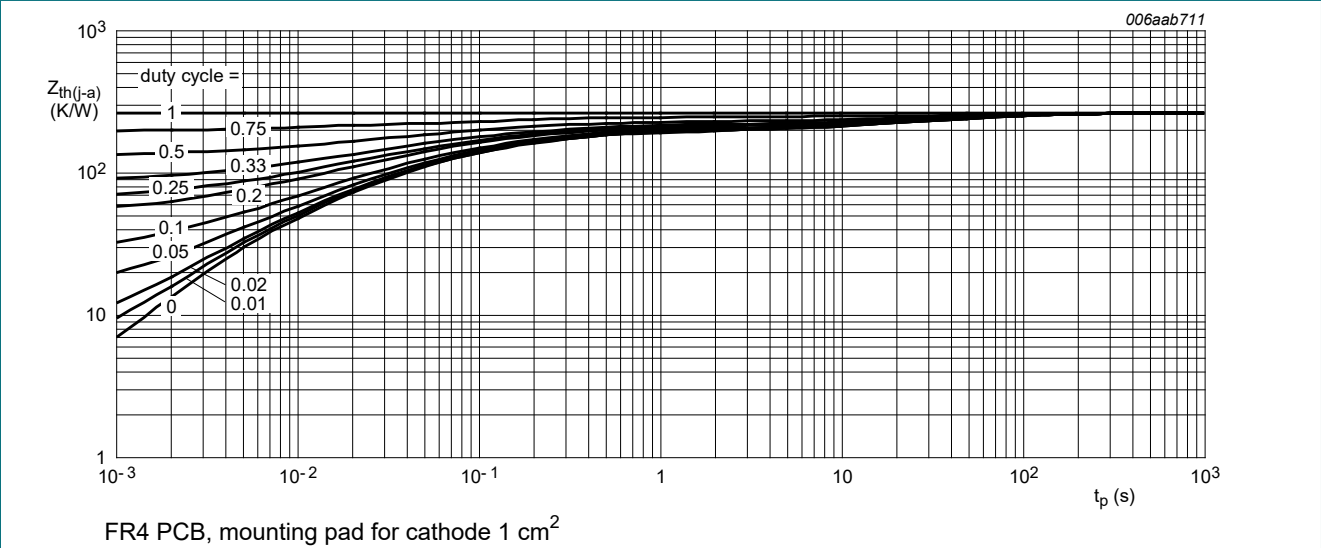


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

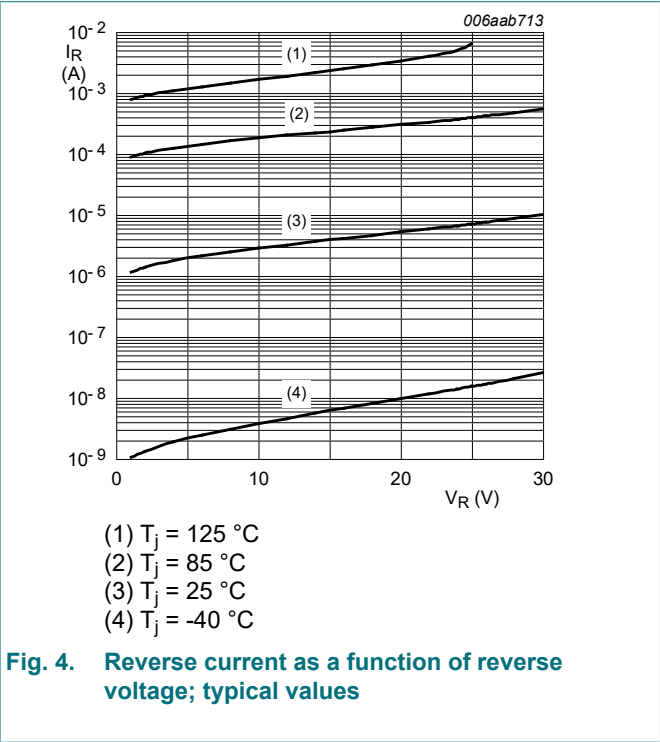
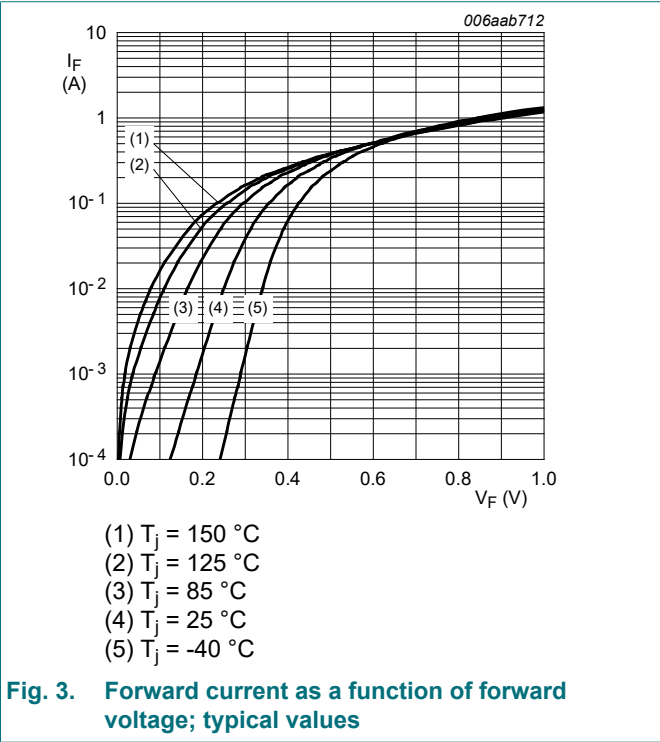
10. Characteristics

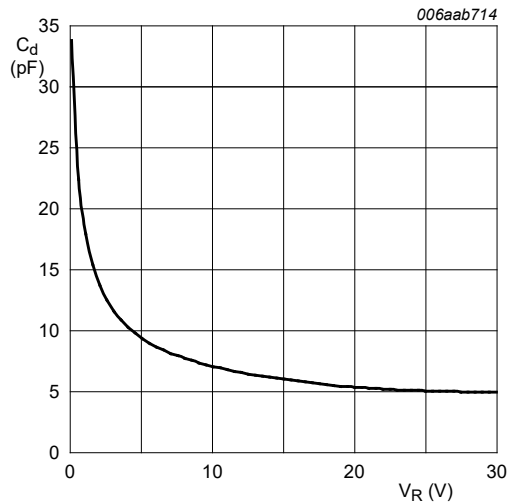
Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.1\text{ mA}$	[1]	-	130	190	mV
		$I_F = 1\text{ mA}$	[1]	-	190	250	mV
		$I_F = 10\text{ mA}$	[1]	-	255	300	mV
		$I_F = 100\text{ mA}$	[1]	-	355	410	mV
		$I_F = 200\text{ mA}$	[1]	-	420	500	mV
I_R	reverse current	$V_R = 10\text{ V}$		-	2.5	30	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$		-	20	25	pF

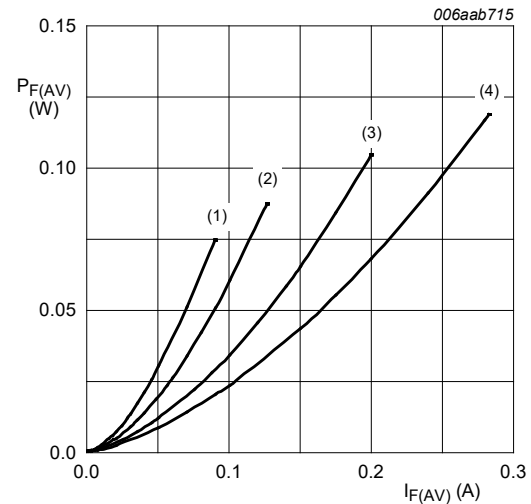
[1] Pulsed test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$





$f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

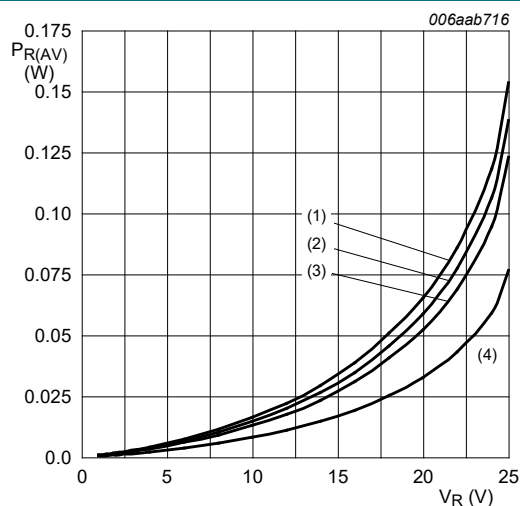
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

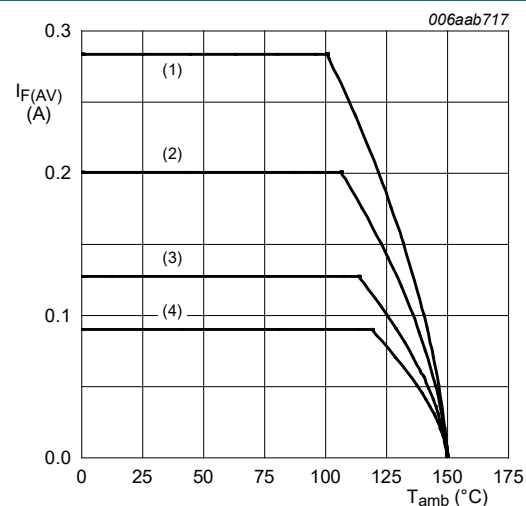
Fig. 6. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values

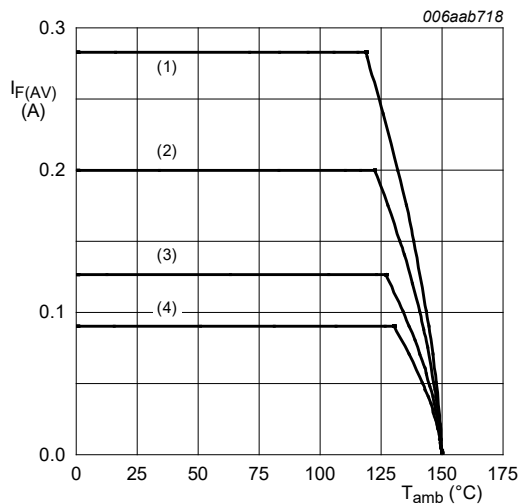


FR4 PCB, standard footprint

$T_j = 150 \text{ }^{\circ}\text{C}$

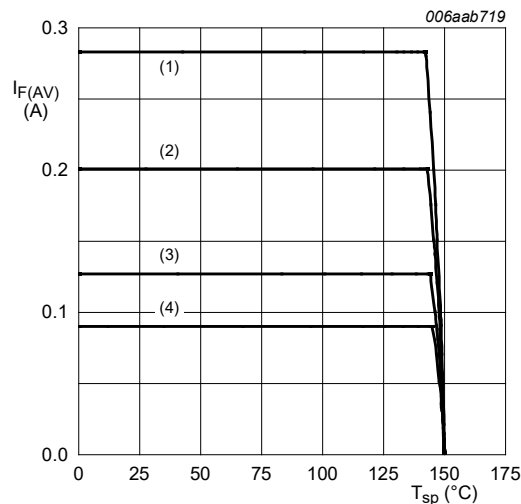
- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20 \text{ kHz}$
- (3) $\delta = 0.2$; $f = 20 \text{ kHz}$
- (4) $\delta = 0.1$; $f = 20 \text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150$ °C
(1) $\delta = 1$; DC
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



$T_j = 150$ °C
(1) $\delta = 1$; DC
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

11. Test information

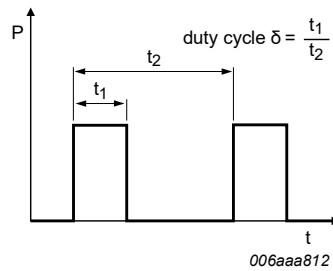


Fig. 11. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

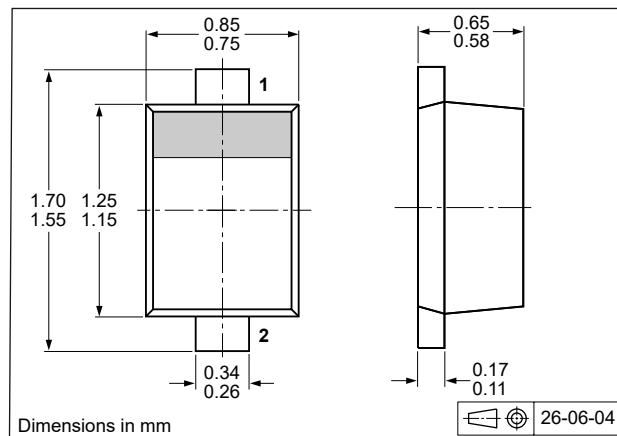


Fig. 12. Package outline SC-79 (SOD523)

13. Soldering

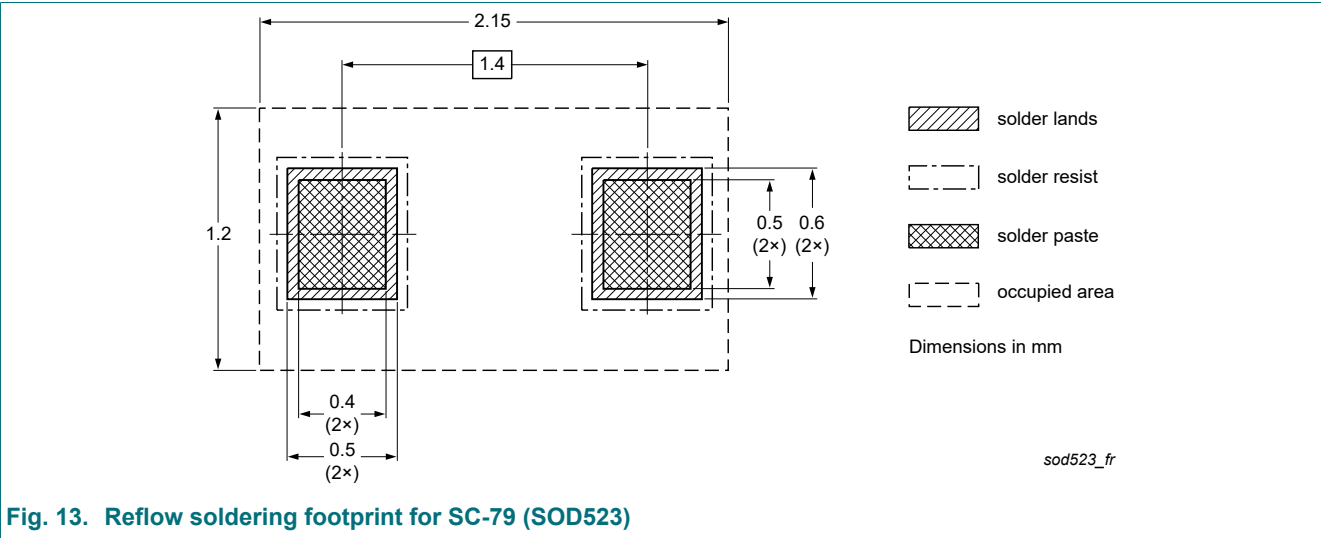


Fig. 13. Reflow soldering footprint for SC-79 (SOD523)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
RB521S30-Q v.2	20260806	Product data sheet	-	RB521S30-Q v.1
Modifications:	Aligned SOD523 package outline drawing			
RB521S30-Q v.1	20230420	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 6 August 2026